



**N-Channel Enhancement MOSFET**



VDS= 30V, ID= 80A

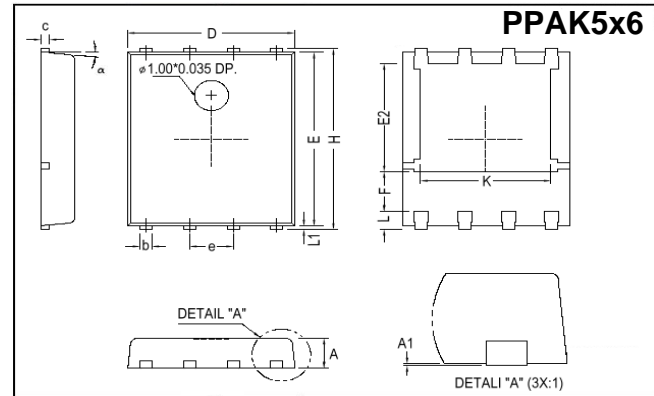
**DESCRIPTION**

The YS80N03BA is the highest performance N-ch MOSFETs with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

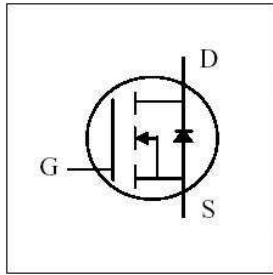
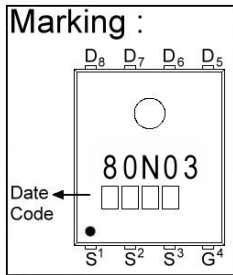
The YS80N03BA meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**FEATURES**

- Advanced high cell density Trench technology
- Excellent CdV/dt effect decline
- Green Device Available
- Super Low Gate Charge
- 100% EAS Guaranteed



REF.	Millimeter			REF.	Millimeter		
	Min.	Nom.	Max.		Min.	Nom.	Max.
A	0.85	1.00	1.15	E	5.70	-	5.90
A1	0.00	-	0.10	e	-	1.27	-
b	0.30	-	0.51	H	5.90	-	6.20
c	0.20	-	0.30	L	-	0.60	-
D	4.80	-	5.00	L1	0.06	-	0.20
F	1.10REF.			$\alpha$	0°	-	12°
E2	3.50REF.			K	3.70	3.90	4.10



**Absolute Maximum Ratings**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$I_D @ T_C=25^\circ C$	80	A
	$I_D @ T_C=100^\circ C$	50	A
Pulsed Drain Current <sup>1,2</sup>	$I_{DM}$	160	A
Total Power Dissipation <sup>4</sup>	$P_D @ T_C=25^\circ C$	53	W
	$P_D @ T_A=25^\circ C$	2	W
Single Pulse Avalanche Energy, L=0.1mH <sup>3</sup>	$E_{AS}$	88	mJ
Single Pulse Avalanche Current, L=0.1mH <sup>3</sup>	$I_{AS}$	42	A
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 ~ +150	°C

**Thermal Data**

Parameter	Symbol	Conditions	Max. Value	Unit
Thermal Resistance Junction-ambient <sup>1</sup>	$R_{\theta JA}$	Steady State	62.5	°C/W
Thermal Resistance Junction-case <sup>1</sup>	$R_{\theta JC}$	Steady State	2.36	°C/W

# DEVICE CHARACTERISTICS

## YS80N03BA

### Electrical Characteristics ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	$BV_{DSS}$	30	-	-	V	$V_{GS}=0, I_D=250\mu\text{A}$
Gate Threshold Voltage	$V_{GS(th)}$	1.0	-	2.5	V	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$
Forward Transconductance	$g_{fs}$	-	18	-	S	$V_{DS}=10\text{V}, I_D=10\text{A}$
Gate-Source Leakage Current	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS} = \pm 20\text{V}$
Drain-Source Leakage Current( $T_J=25^\circ\text{C}$ )	$I_{DSS}$	-	-	1	uA	$V_{DS}=30\text{V}, V_{GS}=0$
Drain-Source Leakage Current( $T_J=125^\circ\text{C}$ )		-	-	10		$V_{DS}=24\text{V}, V_{GS}=0$
Static Drain-Source On-Resistance <sup>2</sup>	$R_{DS(ON)}$	-	-	5.5	m $\Omega$	$V_{GS}=10\text{V}, I_D=20\text{A}$
		-	-	8		$V_{GS}=4.5\text{V}, I_D=10\text{A}$
Total Gate Charge <sup>2</sup>	$Q_g$	-	11.1	-	nC	$I_D=20\text{A}$ $V_{DS}=15\text{V}$ $V_{GS}=4.5\text{V}$
Gate-Source Charge	$Q_{gs}$	-	1.9	-		
Gate-Drain ("Miller") Change	$Q_{gd}$	-	6.8	-		
Turn-on Delay Time <sup>2</sup>	$T_{d(on)}$	-	7.5	-	ns	$V_{DD}=15\text{V}$ $I_D=15\text{A}$ $V_{GS}=10\text{V}$ $R_G=3.3\Omega$
Rise Time	$T_r$	-	14.5	-		
Turn-off Delay Time	$T_{d(off)}$	-	35.2	-		
Fall Time	$T_f$	-	9.6	-		
Input Capacitance	$C_{iss}$	-	1160	-	pF	$V_{GS}=0\text{V}$ $V_{DS}=25\text{V}$ $f=1.0\text{MHz}$
Output Capacitance	$C_{oss}$	-	200	-		
Reverse Transfer Capacitance	$C_{rss}$	-	180	-		
Gate Resistance	$R_g$	-	2.5	3.5	$\Omega$	$f=1.0\text{MHz}$

### Guaranteed Avalanche Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Single Pulse Avalanche Energy <sup>5</sup>	EAS	20	-	-	mJ	$V_{DD}=25\text{V}, L=0.1\text{mH}, I_{AS}=20\text{A}$

### Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	-	-	1.2	V	$I_S=20\text{A}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$
Continuous Source Current <sup>1,6</sup>	$I_S$	-	-	80	A	$V_G=V_D=0\text{V}, \text{Force Current}$
Pulsed Source Current <sup>2,6</sup>	$I_{SM}$	-	-	160	A	

Notes: 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.

2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .

3. The EAS data shows Max. rating. The test condition is  $V_{DD}=25\text{V}, V_{GS}=10\text{V}, L=0.1\text{mH}, I_{AS}=42\text{A}$ .

4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature.

5. The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

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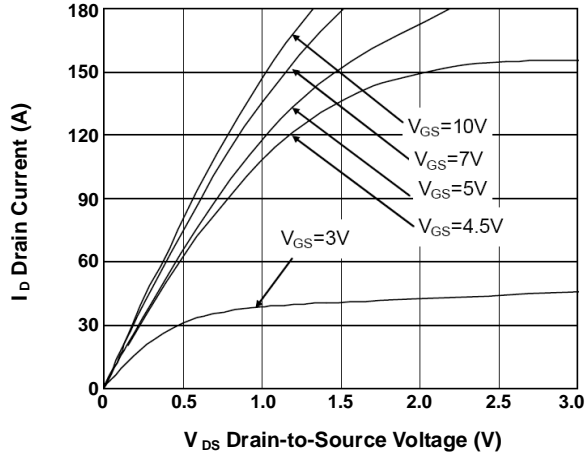


Fig.1 Typical Output Characteristics

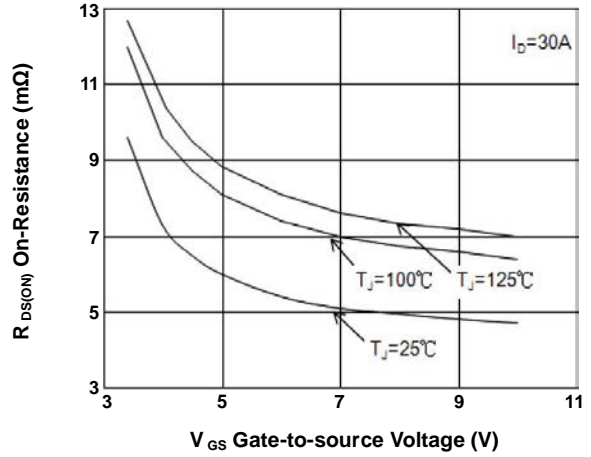


Fig.2 On-Resistance vs. G-S Voltage

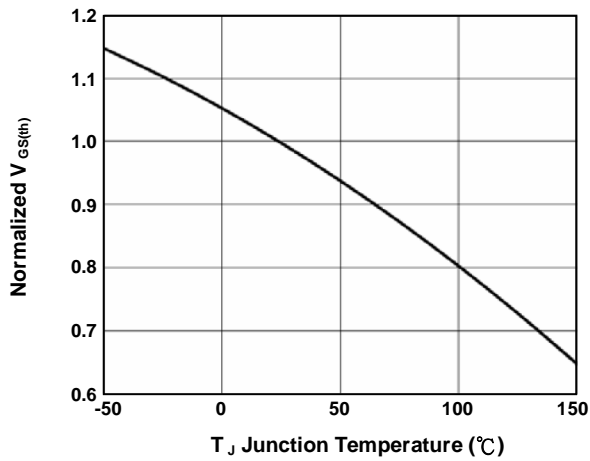


Fig.3 Normalized  $V_{GS(th)}$  vs.  $T_J$

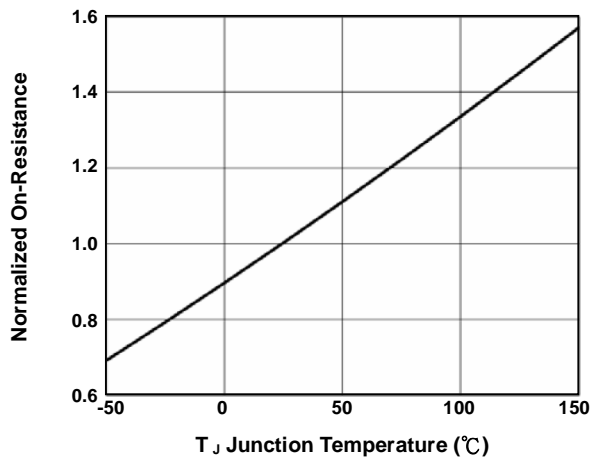


Fig.4 Normalized  $R_{DS(on)}$  vs.  $T_J$

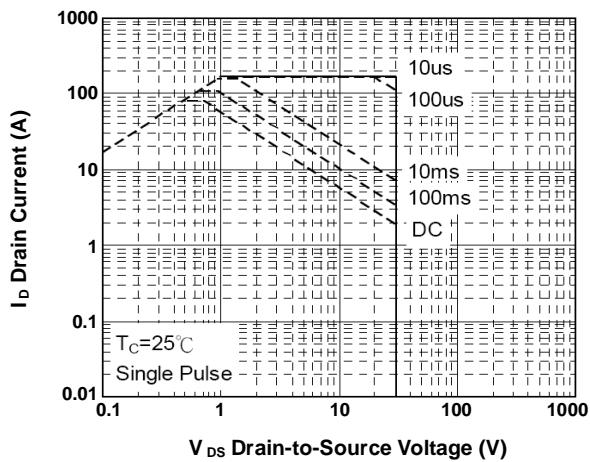


Fig.5 Safe Operating Area

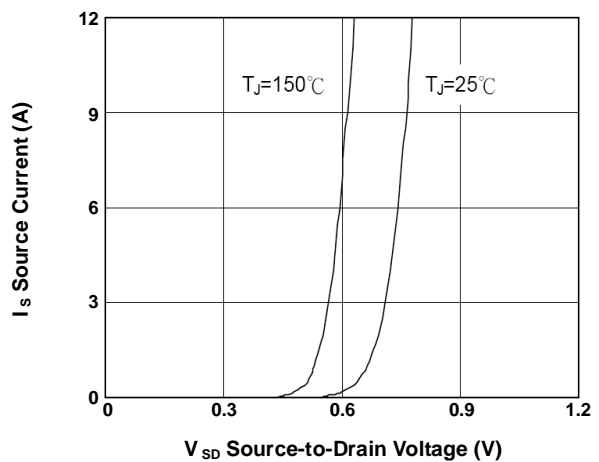


Fig.6 Forward Characteristics of Reverse

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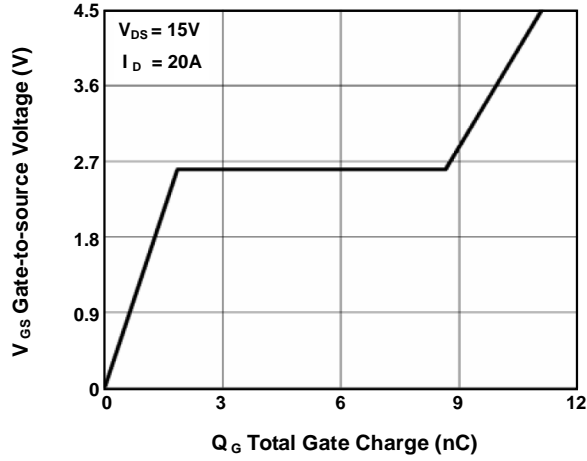


Fig.7 Gate Charge Characteristics

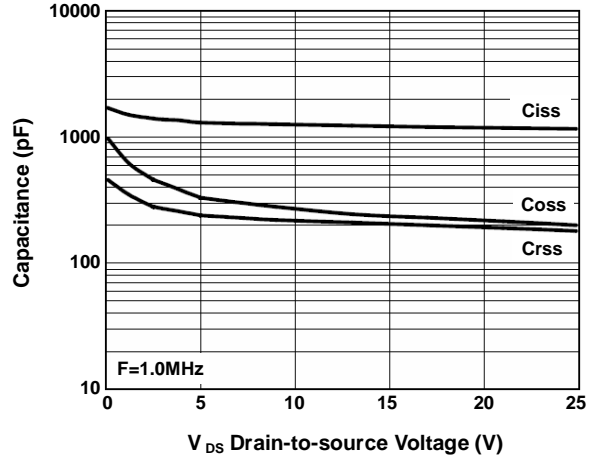


Fig.8 Capacitance Characteristics

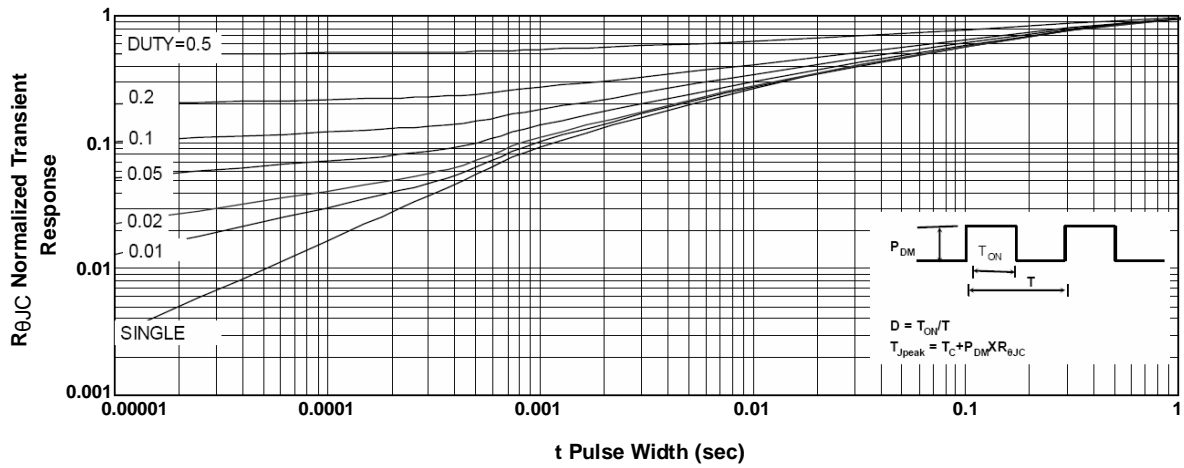


Fig.9 Normalized Maximum Transient Thermal Impedance

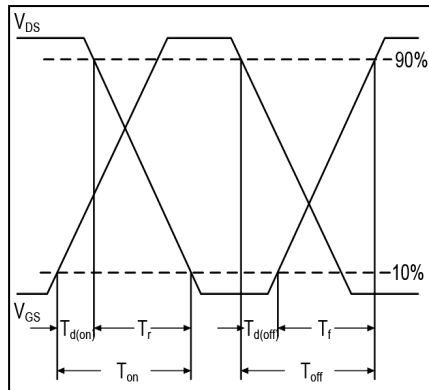


Fig.10 Switching Time Waveform

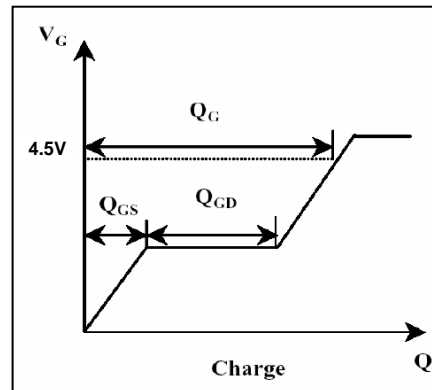


Fig.11 Gate Charge Waveform